

Final Product/Process Change Notification Document #: FPCN21107ZI

Issue Date: 15 June 2016

Title of Change:	Qualification of ON Semiconductor Vietnam (OSV) as an additional Automotive site for Assembly/Test of specified Ultrafast product in DPAK package.				
Proposed first ship date:	15 December 2016 or earlier upon customer approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <gk.sua@onsemi.com></gk.sua@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <cheanching.sim@onsemi.com></cheanching.sim@onsemi.com>				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 6 months prior to implementation of the change or earlier upon customer approval.				
	ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>				
Change Part Identification:	Product from ON Semiconductor Vietnam (OSV) will be marked with site code "VN" prior to the date code while the Seremban device does not have site code marking.				
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other				
Change Sub-Category(s): Manufacturing Site Change/ Manufacturing Process Chan		☐ Material Change ☐ Product specific change	□ Datasheet/Product Doc change☑ Shipping/Packaging/Marking□ Other:		
Sites Affected: All site(s) not applicable		✓ ON Semiconductor site(s) :ON Dong Nai Province, VietnamON Seremban, Malaysia	External Foundry/Subcon site(s)		
Description and Purpose:					
This is the Final Notification to announce the planned qualification of ON Semiconductor Vietnam (OSV) as an additional Assembly and Test site for Automotive discrete DPAK packaged products					
Upon the expiration of this FPCN, a new OSV part number will be available to allow ultrafast product to be sourced from either the existing Seremban or new Vietnam location using the same Bill of Material.					
ON Semiconductor Vietnam (OSV) is a qualified site for DPAK Standard discrete packaged products and is ISO TS16949 certified.					
This product sourced from OSV have been qualified to Automotive requirements and continue remain as Pb-free, Halide free and RoHS compliant.					
Change benefits: Rapid utilization of availability capacity.					
Risk for late release: Limited capacity.					

TEM001092 Rev. H Page 1 of 2



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Reliability Data Summary:

QV DEVICE NAME: MURHD560T4G

PACKAGE: DPAK

Test	Specification	Condition	Interval	Result
HTRB	JESD22-A108	Ta = 150 °C, Tj(est) = 175 °C, bias = 80% of rated V	1008 hrs	0/252
HTSL	JESD22-A103	Ta = 175 °C	1008 hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	15000 cyc	0/252
TC	JESD22-A104	Temp = -65°C to +150°C	1000 сус	0/252
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs	0/252
H3TRB	JESD22-A101	Temp = 85°C, RH=85%, bias = 100V max	1008 hrs	0/252
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/1008
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

Note: AEC1 pager is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file/s

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Current SBN Part Number	New OSV part number	Qualification Vehicle	
NRVUD620CTT4G	SNRVUD620CTT4G	MURHD560T4G	

TEM001092 Rev. H Page 2 of 2